

A METHOD AND SYSTEM FOR UNIVERSAL PACKAGING IN CONJUNCTION
WITH A BACK-END INTEGRATED CIRCUIT MANUFACTURING PROCESS

ABSTRACT OF THE DISCLOSURE

5 A method and system for universal packaging in conjunction with an automated in-line back-end IC manufacturing process. In one method embodiment, the present invention processes a die-strip through a number of integrated in-line processes that function independently of the die size of the die-strip. A control computer maintains a die-strip map database recording the die size of the die-strip.

10 In-line molding and solder ball attachment processes are then performed and function independently of the die size of the die-strip. Processes that are independent of die size provide a universal packaging manufacturing solution. The present invention then accesses the database to determine the die size for cutting the die-strip based on specifications maintained by the electronic die-strip map database.

15 Sorting, testing and finish assembly processes are then performed.